

*Amendments to the Claims*

1-6 (Cancelled)

7. (Currently Amended) A semiconductor package comprising:

a semiconductor chip having a transmission side film bulk acoustic filter and a reception side film bulk acoustic filter formed at an upper surface of a semiconductor substrate accordingly as a plurality of film bulk acoustic resonators are connected serially and in parallel;

a substrate provided with a ceramic body where the semiconductor chip is mounted, a plurality of wire patterns formed at an upper surface of the ceramic body so that the semiconductor chip can be connected thereto by a solder as a flip chip form with an overturned state, and a plurality of conductive ground vias and signal conductive vias connected to the plurality of wire patterns and penetrating the ceramic body; and

a sealing layer for sealing the semiconductor chip of the upper surface of the ceramic body for protection from the external environment, wherein the sealing layer is one selected from epoxy or polymer.

8. (Original) The semiconductor package of claim 7, further comprising a plurality of passive elements at the semiconductor chip.

9. (Original) The semiconductor package of claim 7, wherein the

substrate is one selected from a low temperature co-fired ceramic (LTCC) or a high temperature co-fired ceramic (HTCC).

10. (Original) The semiconductor package of claim 7, wherein the substrate is an LTCC where a plurality of passive elements are formed, and the plurality of passive elements are formed inside the LTCC.

11. (Cancelled)

12. (Currently Amended) The semiconductor package of claim 7, further comprising an air gap for preventing characteristics of ~~the film bulk acoustic filters~~ the transmission side film bulk acoustic filter and the reception side film bulk acoustic filter formed at a ~~lower~~ lower the surface of the semiconductor chip substrate from being deteriorated between the lower surface of the semiconductor chip and the substrate.

13-18 (Cancelled)